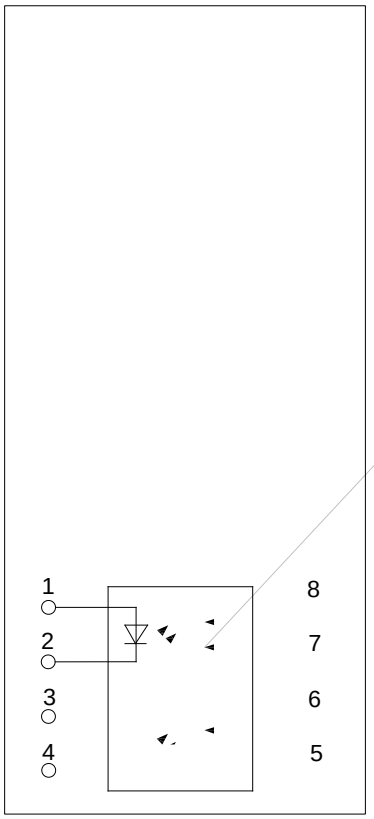
JOR21XD8 Series

Rev.A.1.0

DESCRIPTION:

The products are 8-pin optical relays. The device consists of an AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit in a plastic DIP8 package with different lead forming options. The detector consists of a high-speed photovoltaic diode array and driver circuitry. The products are widely used in isolation in high-speed inspection machines, telephones equipment and computers.



MAIN FEATURES

High isolation 5000 Vrms
Wide variation of load voltage 60V to 600V
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter			Symbol	Value	Unit
Input	Forward Current		I_F	50	mA
	Peak Forward Current		I_{FP}	1	A
	Reverse Voltage		V_R	6	V
	Input Power Dissipation		P_D	75	mW
Output	Load Voltage	JOR212D8	V_O	60	V
		JOR213D8		100	
		JOR214D8		400	
		JOR216D8		600	
	Continuous load current	JOR212D8	I_O	1.25	A
		JOR213D8		1.25	
		JOR214D8		0.1	
		JOR216D8		0.05	
	Output Power Dissipation			600	mW
Total Power Dissipation				675	mW

Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-40~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-40~125	
Soldering Temperature	T_{sol}	260	

NOTE1: 100Hz

NOTE2:

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

ORDERING AND MARKING

[redacted]

Characteristics Curves

FIG.1: LED Dropout Voltage vs. Ambient Temperature

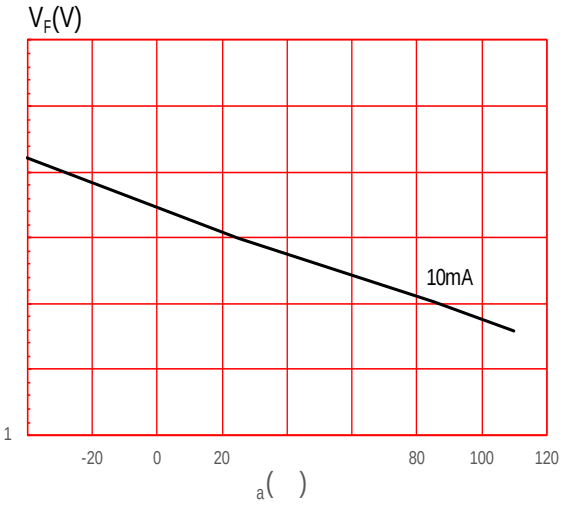
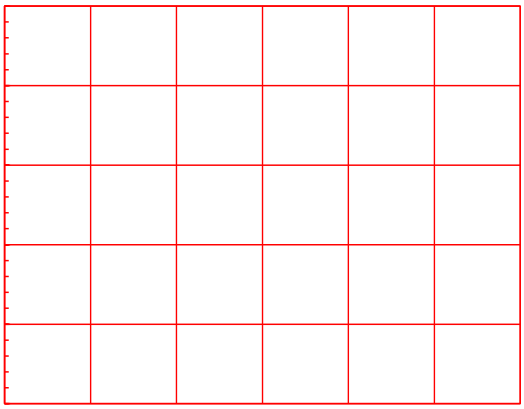
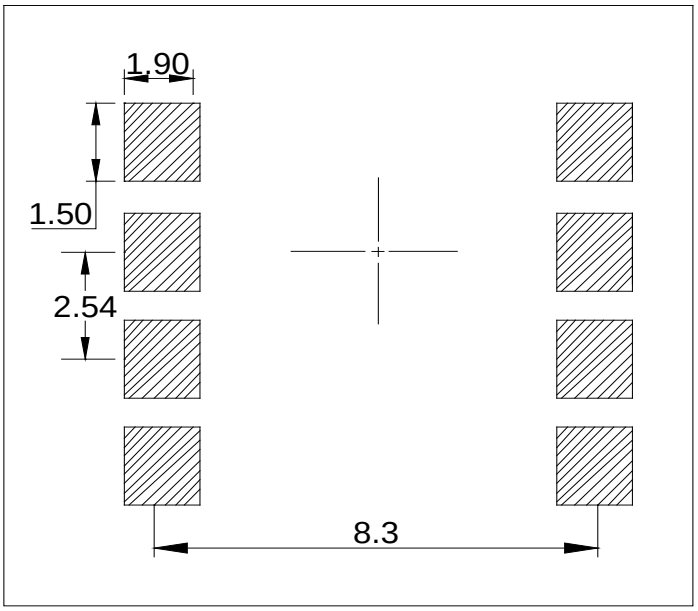


FIG.2: Output Current vs. Output Voltage



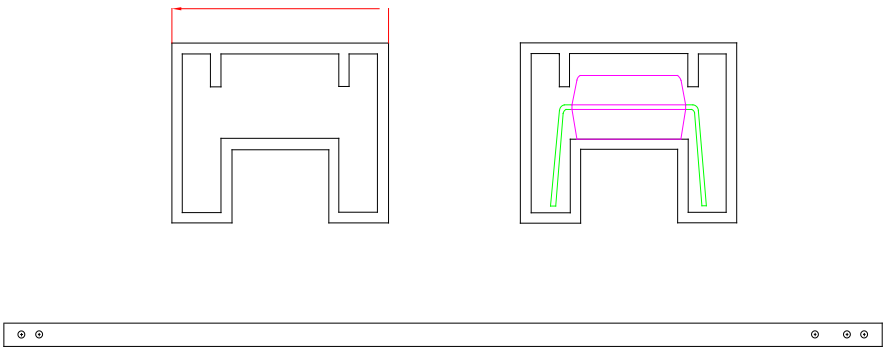
JOR21XD8

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



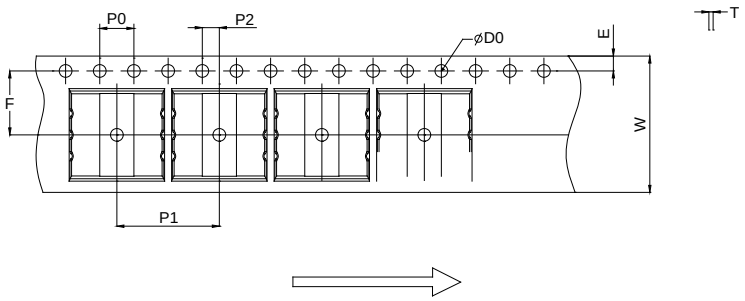
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



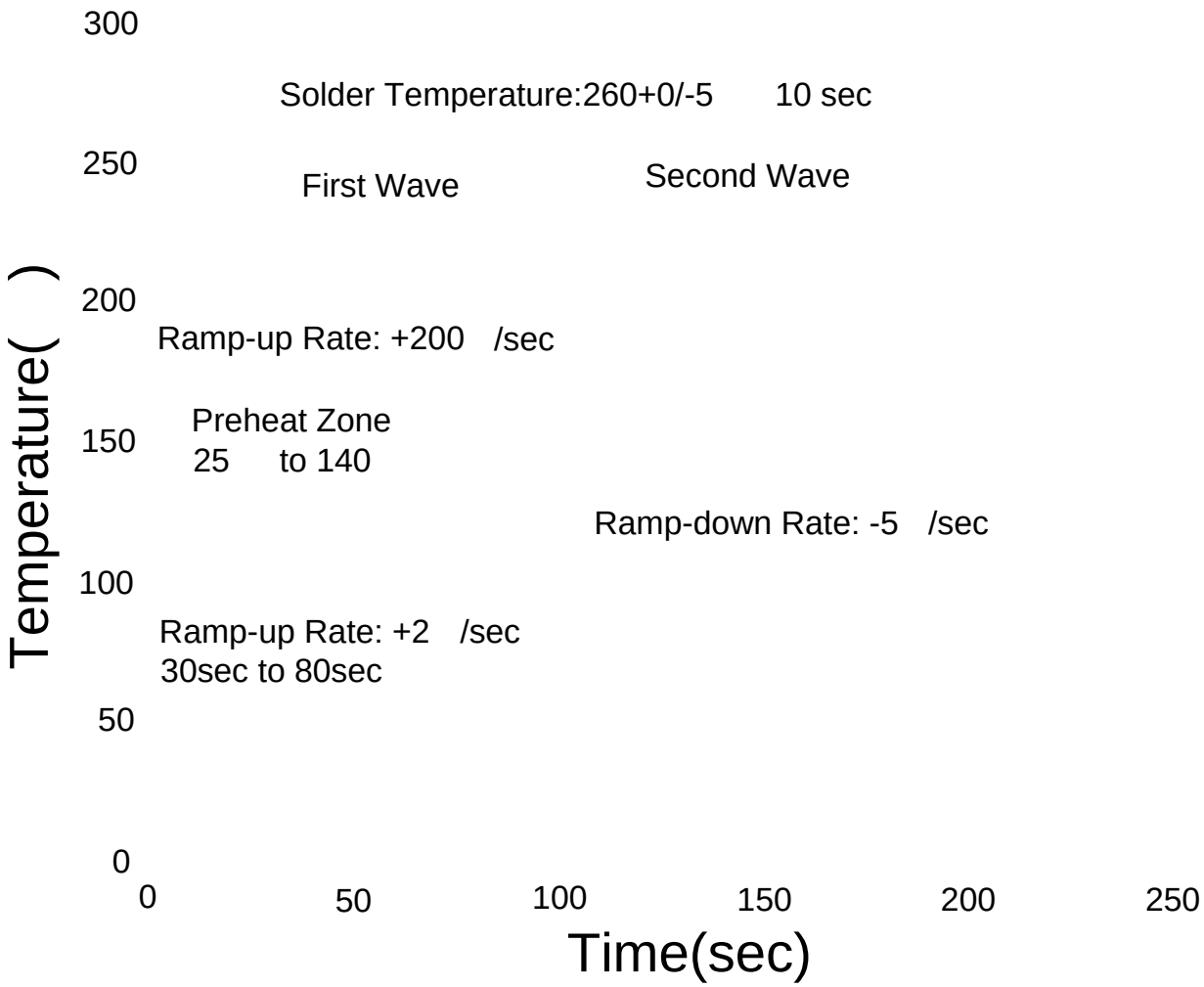
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T3



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

WAVE SOLDERING



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result fri((J)4 06.89 0 Td ( )Tjcd [(f)-189a1)10 neeent(t)]TJ 0 Tc 0 0 Td [(f)ayfm[(a)y(f)89(e)1)e